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Bib Data Sheet

CONFIRMATION NO. 5043

SERIAL NUMBER 10/685,312	FILING DATE 10/14/2003	CLASS 029	GROUP ART UNIT 3729	ATTORNEY DOCKET NO. 2269-5520.1US (02-0676.01)
RULE				

APPLICANTS

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\*\* CONTINUING DATA \*\*\*\*\*

This application is a DIV of 10/409,804 04/09/2003 NOW US PATENT NO. 7,102,217.

\*\* FOREIGN APPLICATIONS \*\*\*\*\*

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 01/16/2004

Foreign Priority claimed 35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance	STATE OR COUNTRY ID	SHEETS DRAWING 4	TOTAL CLAIMS 14-20	INDEPENDENT CLAIMS 1-2
Verified and Acknowledged <i>[Signature]</i>	Examiner's Signature <i>[Signature]</i> Initials				

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TITLE

Interposer substrates with multi-segment interconnect slots, semiconductor die packages including same, semiconductor dice for use therewith and methods of fabrication of INTERPOSER SUBSTRATES WITH MULTISEGMENT INTERCONNECT SLOTS

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